

Name	Multilayer Power Inductors	СОМРО	SITE SPECIFICATION	1/
INAILIE	CMLM1608C100MIT	SPEC#	CMLM1608C100MIT	/ 8
	 1. Scope This specification applies to the CMLM16080 2. Standard and Atmospheric Condition Unless otherwise specified the standard range making measurements and tests is as follows Ambient temperature : 20±15°C Relative humidity : 30~70% If there may be any doubt on the results, measurements in the following limits : Ambient temperature : 25±5°C Relative humidity : 30~70% 3. Ratings 	ons ge of atmos s:	spheric conditions for	uctors

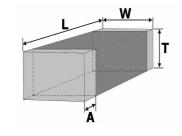
PART NO		SELF-RESONANT FREQUENCY(MHz)	DC RESISTANCE	※ RATED CURRENT
	AT1 MHz 250mV	Min	(Ω)	(mA)Max
CMLM1608C100MIT	10uH±20%	33	0.90±20%	100

%The maximum rated current : the DC current value having temperature increased 40 $^{\circ}$ C after thru DC current 2 hours at ambient temperature.

Regarding to the inductance variability of rated current, please refer to page 2:

Inductance Vs. DC superposition characteristics.

4. Dimensions

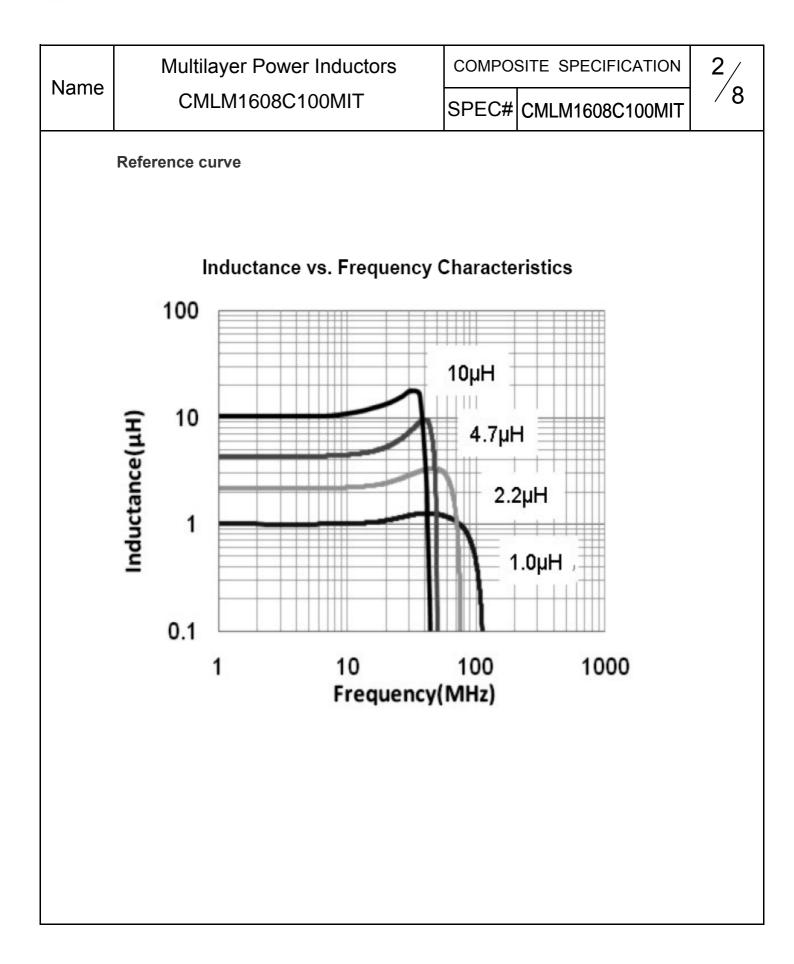


	OPERATING TEMP. RANGE : -55 $^\circ$ C ~ +125 $^\circ$ C					
	STORAG	E TEMF	P. RANGE	E∶-10°C ~	+40 °C	
unit:	TYPE	L	W	Т	A(m/m)	
mm	CMLM1608	1.6±0.15	0.8±0.15	0.8±0.15	0.2~0.6	
(inch)	CIVILIVITOOO	(0.063±0.006)	(0.031±0.006)	(0.031±0.006)	(0.008~0.024)	

PLANNED BY	CHECKED BY	APPROVED BY	
LUN	TINA	Chi Chi Huang	C

Па ybermaxtech.com







Namo	Multilayer Power Inducto	ors	COMPOSITE SPECIF			ICATION	3/
Name	CMLM1608C100MIT		SPEC# CMLM160		CMLM1608	C100MIT	/ 8
•	eflow soldering conditions Pre-heating should be in such a way the surface is limited to 150° C max. Also coordinate way that the temperature difference is limited Insufficient pre-heating may cause crack quality. Products should be soldered within the find The excessive soldering conditions may repeated, allowable time is the accumula $\begin{array}{c} \bigcirc & 270 \\ & 10 \\ & 250 \\ & 230 \\ & 10 \\ & 230 \\ & 10 \\ & 20 \\ & 30 \\ & 10 \\ & 10 \\ & 20 \\ & 30 \\ & 10 \\ & 10 \\ & 20 \\ & 30 \\ & 10 \\ & $	oling into s mited to 10 cks on the following a cause the	olvent 00°C ma ferrite, llowable	after ax. resul e rang	soldering should lting in the deter ge indicated by	d be in such rioration of p the slanted I	a roduct ine.
Tem	perature Profile) 40 50 6	50 70				
rein			A S	lone	of temp. rise	: 1 to 5	°C/sec
	Main heating —————		Н	eat t		50 to 150	sec
^ [_]	230°C		\square \square \square		emperature	120 to 180	°C
					of temp. rise	1 to 5	°C/sec
dimetaria Norm A temp	re-heating				ver 230°C	90~120	sec
e Norm			г Р	eak t	emperature	255~260	°C
			E P	eak h	old time	10 max.	sec
			Ν	No. of	mounting	3	times
	Time [sec] (Melting area	a of solder	r)				
6 1 D	eworking with soldering iron						
0-1 K	Preheating	15	0℃,1r	ninute	<u> </u>	1	
	Tip temperature		0°C ma			_	
	Soldering time		econds			-	
	Soldering iron output		w max.				
	End of soldering iron	φ 3	mm ma	ax.			
	• Reworking should be limited to only or	ne time.				_	
Note	: Do not directly touch the products with	the tip of t	he sold	lering	iron in order to	1	
	prevent the crack on the ferrite material	due to the	therma	al sho	ck.		
6-2 S	older Volume					er Limit	
	Solder shall be used not to be exceed the up	oper limits a	s showr	ı belov	w. <u>Reco</u>	ommendable	
	Accordingly increasing the solder volume				=		
	increased. Exceeding solder volume ma	y cause th	e failur	e of r	nechanical or e	lectrical	
	performance.						



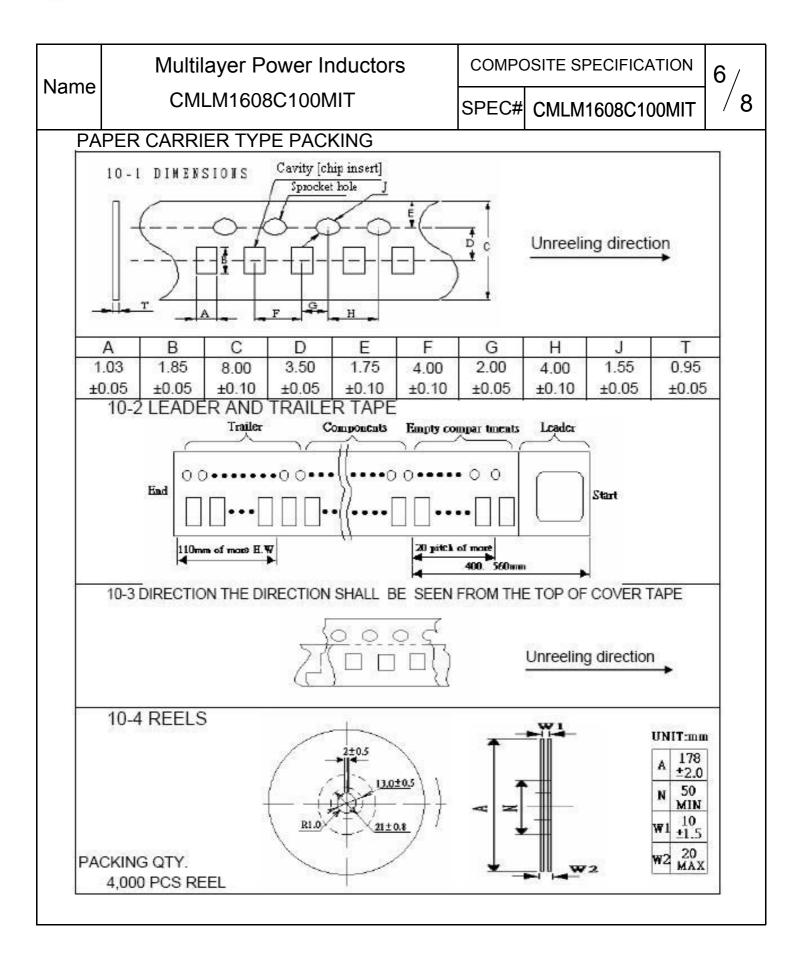
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ame		-			4	
		CMLM1608C100MIT	SPEC#	CMLM1608C100MIT	/ 8	
	ana 7-2 DC I DC met					
I	TEM	Specification		Test Conditions		
Te	erminal	Without deformation cases	Solder chip	on PCB and applied 10N		
St	trength	inductance shall be satisfied $\pm 20\%$	(1.02Kgf) fo	or 10 sec		
		DC resistance shall be satisfied.	Citere do	CHIP F		
	bstrate	Without deformation cases,	After soldering a chip to a test substrate,			
Ben	ding Test	inductance shall be satisfied ± 20%	bend the substrate by 3mm hold for 10s			
		DC resistance shall be satisfied.	and then re	eturn.		
			Soldering shall be done in accordance			
			with the recommended PC board pattern			
			and reflow	soldering.		
			unit : mm		Stilling V	
Re	sistance	No visible damage	Solder Ten	וp. : 265±3℃		
to So	older Heat	Electrical characteristics and mechanic				
		characteristics shall be satisfied.	-	: 100°C to 150°C, 1 minute.		
				ent to be made after keeping	at room	
		Consult standard MIL-STD-202	temp for 24			
Sal	dorability	METHOD 210		<u>-3Ag-0.5Cu</u>		
500	derability	95% min. coverage of all metabolised area	Solder temp. : 240±5°C Immersion time : 3±1 sec			
				-3Ag-0.5Cu		
		Consult standard J-STD-002		l or ig-0.00u		
L			1			



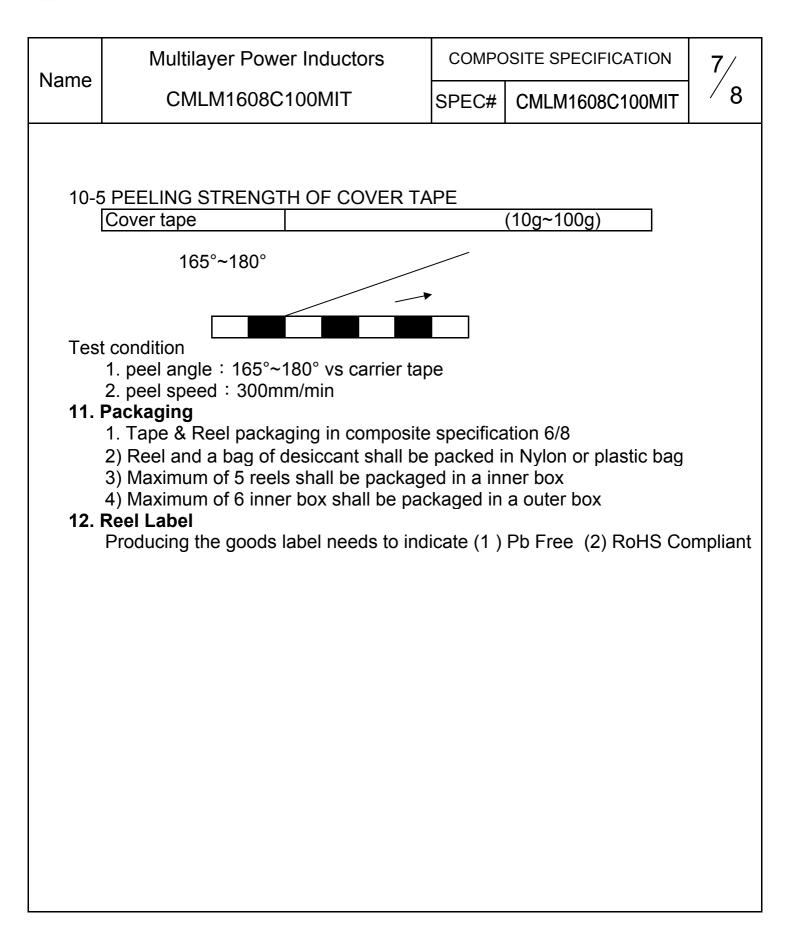
CMLM1608C100MIT

Nore	Multilayer Power Inductors cc		OSITE SPECIFICATION	5/
Name	CMLM1608C100MIT	SPEC#	CMLM1608C100MIT	78
	RELIABILITY AND TEST CONDITIONS 9-1 HIGH TEMPERATURE RESISTANCE a. Performance specification 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Temperature: 125°C ±2°C 2.Testing time : 1000±12hrs 3.Measurement : After placing at room ambient t 9-2 Biased Humidity RESISTANCE a.Performance specification 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Humidity: 85 ± 5%RH 2. Temperature: 85°C ±2°C 3.Testing time: 1000 ± 12 hours 4.Measurement : After placing at room ambient t 9-3 TEMPERATURE CYCLE a.Performance specification 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1. Low Temperature: - 55°C ±5°C kept stabilized	emperature f e emperature f ie for 30 minute	or 24 hours minimum s each	
	 2. High Temperature: 125℃ ±5℃ kept stabilized to 2. Cycle : 1000 cycles 3. Measurement : After placing for 24hours mining 4. step155℃ temp±3℃ 30±3 minutes step2. Room temperature 2to5 minutes step3. +125℃ temp±3℃ 30±3 minutes step4. room temperature 2to5 minutes 9-4 VIBRATION TEST a.Performance specification 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.Frequency and Amplitude:10-2000-10Hz 2.Direction:X,Y,Z. 3.Test duration:4 hours for each direction,12hour 9-5 Mechanical Shock TEST a.Performance specification 1.Appearance : no mechanical damage 2.Interction:X,Y,Z. 3.Test duration:4 hours for each direction,12hour 9-5 Mechanical Shock TEST	num at room a ie rs in total.		
	 b.Test condition peak acceleration : 100 g's Duration of pulse : 6 ms Waveform : Half-sine Velocity change : 12.3 ft/sec Direction : X ' Y ' Z (3axes/3 times) 9-6 Operational Life Performance specification Appearance : no mechanical damage Inductance shall be with ±20% of the initial value Test condition Temperature: 125°C ±2°C 			
9.1 R	 2.Testing time : 1000±12hrs 3.Measurement : After placing at room ambient t 9-7 Electrostatic discharge test a. Performance specification 1.Appearance : no mechanical damage 2.Inductance shall be with ±20% of the initial value b.Test condition 1.ESD voltage: 15k volts 2.Mode 1:150 pF/330 Ohm 3.Mode 2:150 pF/2000 Ohm REMARK reliability test customers if there are special requirements 	ie		











	Multilayer Power Inductors	Multilayer Power Inductors COMPOS		8 /
NAME	CMLM1608C100MIT	SPEC#	CMLM1608C100MIT	8 / 8
13. \$	Storage			I
	13-1The solderability of the external electrode may	/ be		
	deteriorated if packages are stored where the	ey are		
	exposed to high humidity. Packages must be	stored		
	at 40 $^\circ\!\mathrm{C}$ or less and 70% RH or less.			
	13-2 The solderability of the external electrode ma	y be		
	deteriorated if packages are stored where the	ey are		
	exposed to dust or harmful gas (hydrogen ch	loride,		
	sulfurous acid gas or hydrogen sulfide).			
	13-3 Packaging material may be deformed if packa	ages are		
	stored where they are exposed to heat or dir	ect sun-		
	light.			
	13-4 Minimum packages, such as polyvinyl heat-	seal packa	ges	
	shall not be opened until just before they are	used.		
	If opened, use the reels as soon as possible.			
	13-5 Solderability specified in composite specificat	ion 4/8 sha	ll be	
	for 6 months from the date of delivery on cor	dition that		
	they are stored at the environment specified	clause		
	13-1 & 13-2.			
	For those parts which passed more than 6 m	onths shall		
	be checked solderability before it is used.			

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